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JUL 07 2008

LISTING OF CLAIMS:

1. (Original): A method of manufacturing liquid crystal display device comprising the steps of:

forming an organic material film having projections and depressions, using a photo-embossing material, on an insulating film on an underlying electrode in a thin-film transistor of an active-matrix liquid crystal display device;

exposing said insulating film in a contact-hole-forming-area by reducing a thickness of said organic material film by a dry etching to said organic material film; and

forming a contact hole by a dry etching to the exposed insulating film.

2. (Original): A method as claimed in claim 1, further comprising the steps of:

exposing said underlying electrode in forming said contact hole; and

contacting the exposed underlying electrode with a reflective electrode by forming said reflective electrode on the resulting structure.

3. (Original): A method as claimed in claim 1, wherein said photo-embossing material is a material patternable by an exposing step and a baking step.

4. (Original): A method as claimed in claim 3, wherein said organic material film is formed by exposing and baking said photo-embossing material in forming said organic material film.

5. (Original): A method as claimed in claim 4, wherein a halftone mask or a diffraction mask is used in exposing.

6. (Currently amended): A method as claimed in claim 1, wherein the dry processes are performed from the step of forming said organic material film to the step of forming said contact hole.

7. (Currently amended): A method as claimed in claims claim 1, wherein the step of exposing said insulating film and the step of forming said contact hole are performed in a single apparatus.

8. (Currently amended): A method as claimed in claim 1, wherein ~~the~~ dry etching process in the step of exposing said insulating film is performed in an Inductively Coupled Plasma mode or a reactive ion etching mode.

9. (Original): A method as claimed in claim 1, wherein said liquid crystal display device is a reflective type of liquid crystal display device or a transfective type of liquid crystal display device.

10. (New): A method as in claim 1, wherein the projections and depressions of the organic material film are formed by subjecting the photo-embossing material to a mask and exposure to light, wherein the projections and depressions in the organic material film include a thinnest region corresponding to the contact-hole-forming-area.

11. (New): A method as in claim 10, wherein the mask comprises a light shield portions corresponding to the projections, semi-transparent regions corresponding to the depressions, and a transparent portion corresponding to the thinnest region in the organic material film.

12. (New): A method as in claim 10, wherein the insulating film is exposed by dry etching the thinnest region of the organic material film.

13. (New): A method of manufacturing a liquid crystal display device comprising:
forming a thin-film transistor on a substrate;
forming an insulating film over the thin-film transistor;
disposing an organic material film above the insulating film;
forming projections and depressions in the organic material film, including a thinnest region corresponding to a contact-hole-forming-area;
dry etching the thinnest region of the organic material film to expose a region of the insulating film; and
dry etching the exposed region of the insulating film to form a contact hole.

14. (New): The method as in claim 13, wherein the organic material film comprises a photo-embossing material, wherein the projections and depressions are formed by subjecting the photo-embossing material to a mask and exposure to light.

15. (New): The method as in claim 14, wherein the mask comprises a light shield portions corresponding to the projections, semi-transparent regions corresponding to the depressions, and a transparent portion corresponding to the thinnest region in the organic material film.

16. (New): The method as in claim 13, further comprising the steps of forming an electrode layer below the insulating layer, wherein a region of the electrode is exposed after the contact hole is formed; and forming a reflective electrode above the projections and depressions and the exposed region of the electrode layer, wherein the reflective electrode contacts the exposed region of the electrode layer.

17. (New): The method as in claim 13, wherein only dry processes are performed from forming said projections and depressions in the organic material film to forming said contact hole.

18. (New): The method as in claim 13, wherein dry etching the thinnest region of the organic material film and dry etching the exposed region of the insulating film are performed in a single apparatus.

19. (New): The method as in claim 13, wherein dry etching to expose the insulating film is performed in an inductively coupled plasma mode or a reactive ion etching mode.

20. (New): The method as in claim 13, wherein said liquid crystal display device is a reflective type liquid crystal display device or a transflective type of liquid crystal display device.